

HMC435MS8G

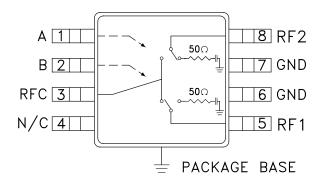
SPDT NON-REFLECTIVE SWITCH, DC - 4.0 GHz

Typical Applications

The HMC435MS8G is ideal for:

- Basestation Infrastructure
- MMDS & 3.5 GHz WLL
- CATV/CMTS
- Test Instrumentation

Functional Diagram



Features

High Isolation: 60 dB @ 1 GHz

50 dB @ 2 GHz

Positive Control: 0/+5V

51 dBm Input IP3

Non-Reflective Design

MS8G SMT Package, 14.8 mm²

General Description

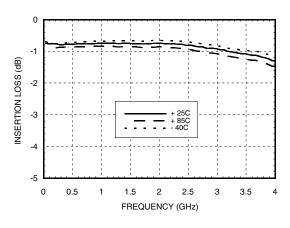
The HMC435MS8G is a non-reflective DC to 4 GHz GaAs MESFET SPDT switch in a low cost 8 lead MSOP8G surface mount package with an exposed ground paddle. The switch is ideal for cellular/PCS/3G basestation applications yielding 50 to 60 dB isolation, low 0.8 dB insertion loss and +50 dBm input IP3. Power handling is excellent up through the 3.5 GHz WLL band with the switch offering a P1dB compression point of +31 dBm. On-chip circuitry allows positive voltage control of 0/+5 Volts at very low DC currents.

Electrical Specifications, $T_A = +25^{\circ} C$, Vctl = 0/+5 Vdc, 50 Ohm System

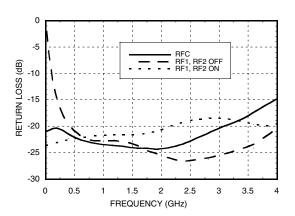
| Parameter | Frequency | Min. | Тур. | Max. | Units |
|---|---------------|------|------|------|-------|
| | DC - 2.5 GHz | | 0.8 | 1.0 | dB |
| Insertion Loss | DC - 3.6 GHz | | 1.2 | 1.5 | dB |
| | DC - 4.0 GHz | | 1.5 | 1.8 | dB |
| | DC - 1.0 GHz | 56 | 60 | | dB |
| | DC - 2.0 GHz | 46 | 50 | | dB |
| Isolation (RFC to RF1/RF2) | DC - 2.5 GHz | 43 | 47 | | dB |
| | DC - 3.6 GHz | 37 | 41 | | dB |
| | DC - 4.0 GHz | 30 | 35 | | dB |
| | DC - 2.5 GHz | 15 | 20 | | dB |
| Return Loss (On State) | DC - 3.6 GHz | 13 | 17 | | dB |
| | DC - 4.0 GHz | 11 | 15 | | dB |
| Return Loss (Off State) | 0.5 - 4.0 GHz | 16 | 21 | | dB |
| Input Power for 1 dB Compression | 0.5 - 4.0 GHz | 27 | 31 | | dBm |
| | 0.5 - 1.0 GHz | 48 | 51 | | |
| Input Third Order Intercept | 0.5 - 2.5 GHz | 45 | 48 | | dBm |
| (Two-Tone Input Power = +7 dBm Each Tone) | 0.5 - 4.0 GHz | 41 | 45 | | |
| Switching Speed | DC - 4.0 GHz | | | | |
| tRISE, tFALL (10/90% RF) | | | 40 | | ns |
| tON, tOFF (50% CTL to 10/90% RF) | | | 60 | | ns |



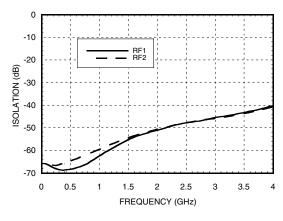
Insertion Loss



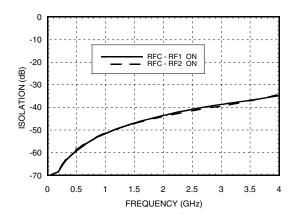
Return Loss



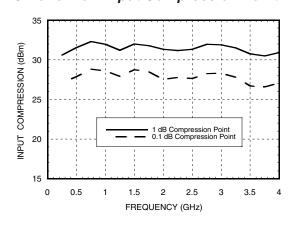
Isolation Between Ports RFC and RF1 / RF2



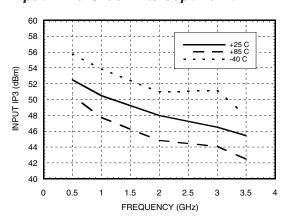
Isolation Between Ports RF1 and RF2



0.1 and 1 dB Input Compression Point



Input Third Order Intercept Point





Absolute Maximum Ratings

| Control Voltage Range | -0.5 to +7.5 Vdc | |
|-----------------------------|------------------|--|
| Storage Temperature | -65 to +150 °C | |
| Operating Temperature | -40 to +85 °C | |
| RF Input Power Vctl = 0/+5V | +31 dBm | |

Control Voltages

*Control Input Tolerances are ± 0.2 Vdc

| State | Bias Condition* | |
|-------|------------------------|--|
| Low | 0 Vdc @ 25 μA Typical | |
| High | +5 Vdc @ 25 μA Typical | |

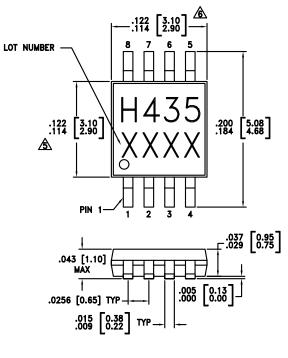
Truth Table

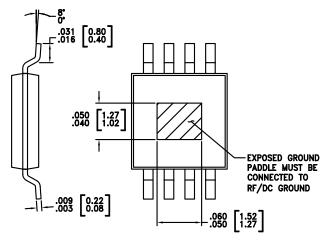
| Control Input | | Signal Path State |
|---------------|------|-------------------|
| А | В | RFC to: |
| Low | High | RF1 |
| High | Low | RF2 |

DC blocks are required at ports RFC, RF1, RF2.

Do not operate continuously at RF power input greater than 1 dB compression and do not "**Hot Switch**" power levels greater than +24 dBm (control = 0/+5 Vdc).

Outline Drawing





NOTES:

- PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
- 2. LEADFRAME MATERIAL: COPPER ALLOY
- 3. LEADFRAME PLATING: Sn/Pb SOLDER
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- $\stackrel{\frown}{\triangle}$ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 7. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

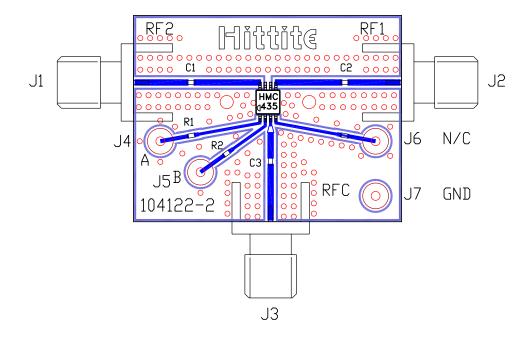


Pin Descriptions

| Pin Number | Function | Description | Interface Schematic |
|------------|---------------|--|---------------------|
| 1 | А | See truth and control voltage tables. | 0———R |
| 2 | В | See truth and control voltage tables. | c |
| 3, 5, 8 | RFC, RF1, RF2 | These pins are DC coupled and matched to 50 Ohms. Blocking capacitors are required. | |
| 4 | N/C | Not Connected | |
| 6, 7 | GND | Package bottom has exposed metal paddle that must be connected to PCB RF ground as well. | |



Evaluation PCB



List of Material

| Item | Description |
|---------------------------------------|-----------------------------|
| J1 - J3 | PC Mount SMA RF Connector |
| J4 - J7 | DC Pin |
| C1 - C3 | 100 pF Capacitor, 0402 Pkg. |
| R1 - R2 | 100 Ohm Resistor, 0402 Pkg. |
| U1 | HMC435MS8G SPDT Switch |
| PCB* | 104122 Evaluation PCB |
| * Circuit Board Material: Rogers 4350 | |

Note: Pin J6 is unused and need not be connected.

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 ohm impedance and the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.



Notes:

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.